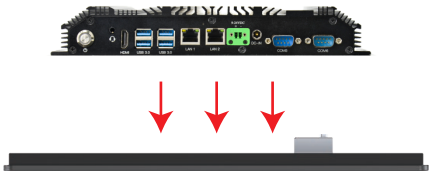
10.1" Modular Industrial Panel Based on NXP i.MX 8M Plus CPU

Main Features:

- Three touch screen sizes for options, including 10.1", 11.6" and 15.6"
- 2 x 10/100/1000Mbps RJ45 network, 2.4GHz & 5GHz Wi-Fi (4G optional)
- 4 x RS232, 2 x RS485/RS232, 4 x USB 3.0 Host, 2 x USB 2.0 Host
- 1 x HDMI, 1 x 3.5mm headphone



Description:

The i.MX 8M Plus of applications processors combines scalable platforms with broad levels of integration and power-efficient processing capabilities. The modular panel provides flexible solutions based on quad core i.MX 8M Plus, targeted at both commercial and industrial applications.

It consists of a front display screen and a back-end fanless computer, which allows cus-tomers to select the back-end module with an appropriate processor, and flexibly match it to a 10.1"/ 11.6"/ 15.6" touch screen. In this way, it helps to reduce time and cost in the future maintenance, upgrade and production process.

Specification:

System	
CPU	NXP i.MX 8M Plus (default), 4 x ARM Cortex-A53, comes with an integrated neural processing unit (NPU) that delivers up to 2.3 TOPS. Industrial grade CPU runs at 1.6GHz, and commercial grade CPU runs at up to 1.8GHz. (i.MX 8M Plus series CPU optional)
Memory	2GB LPDDR4 (4GB/8GB optional)
Storage	16GB eMMC (8GB/32GB/64GB/128GB/256GB optional)
OS	Android 11, Yocto-L5.10.72_2.2.0, Ubuntu 22.04, Windows 10 IoT Enterprise Note: 4GB/8GB LPDDR4 supports Windows 10 IoT, recommend 8GB version.
Video & Audio	
Touch Screen	10.1" 1280 x 800 10-point capacitive touch screen (11.6"/15.6" screen optional)
Display Interface	1 x HDMI
Audio Interface	1 x 3.5mm headphone
Front I/O	
Power Switch	1 x Power switch
Power Input	1 x DC IN, supports 5.5mm x 2.1mm plug; 1 x 2Pin 3.81mm Phoenix
Network	2 x 10/100/1000Mbps RJ45 network port, 2.4GHz & 5GHz Wi-Fi 4G (optional)
USB	4 x USB 3.0 Host Type-A
COM	2 x RS485/RS232 (RS485 for default)
Rear I/O	
COM	4 x RS232
USB	2 x USB 2.0 Host Type-A
Antenna Connectors	1 x WIFI antenna connector, 1 x 4G antenna connector (optional)
Mechanical & Environmental	
Enclosure	Black color, made of aluminum alloy
Dimension	261mm x 136mm x 39mm (Back-end computer module, not include the screen)
Weight	2.9kg
Cooling	Fanless design, with radiator for heat dissipation
Mounting	VESA
Operating Temp.	Commercial: 0°C~+70°C Extended Commercial: -20°C~+70°C Industrial: -40°C~+85°C

Order Information:

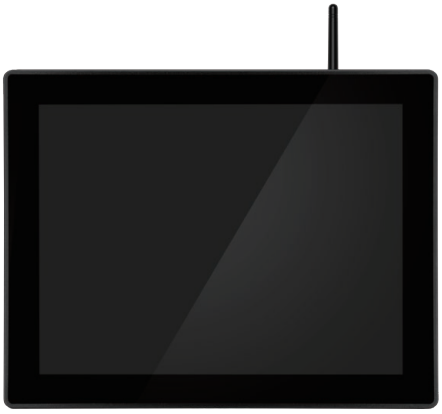
CPU	Screen	Memory	Storage	LAN	HDMI	Audio	COM	USB	Power
i.MX 8M Plus	10.1"	2GB	16GB	2	1	Yes	4*RS232 2*RS485	4*USB 3.0 2*USB 2.0	DC IN

Industrial Panel Photos:

Back-end Computer Photos:

Other Panel Sizes For Options:

11.6 Inches



15.6 Inches

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Beyond the Embedded Deployment

ABOUT POLYHEX

As a board level and system level designer and manufacturer, Polyhex, always delivers best-in-class embedded computing solutions based on both ARM and X86 architecture, including hardware customization and software debugging etc. Partnered with silicon vendors like Intel, NXP, ST, Rockchip, Allwinner and so on, we have earned trust from clients worldwide in over 100 countries. Polyhex is also certified with ISO9001 and ISO13485 for the self-owned manufacture facility.